

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPB80P03P4L-07	**Issued**	14. May 2021
MA#	MA002921200		
Package	PG-TO263-3-2	**Weight***	1559.45 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.218	0.14	0.14	1422	1422
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.50	19.53	194957	195211
wire	non noble metal	aluminium	7429-90-5	7.873	0.50	0.50	5049	5049
encapsulation	inorganic material	zincoxide	1314-13-2	6.845	0.44		4390	
	miscellaneous	miscellaneous	-	27.382	1.76		17559	
	plastics	epoxy resin	-	102.682	6.58		65845	
	inorganic material	silicondioxide	60676-86-0	547.639	35.12	43.90	351174	438968
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6192	6192
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148
solder	non noble metal	tin	7440-31-5	0.043			27	
	noble metal	silver	7440-22-4	0.053			34	
	non noble metal	lead	7439-92-1	2.031	0.13	0.13	1302	1363
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.12	35.17	351190	351647
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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